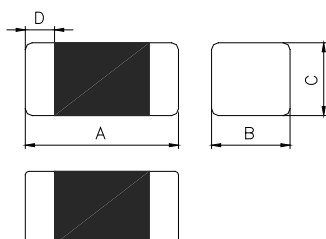


1. Features

1. Monolithic inorganic material construction.
2. Closed magnetic circuit avoids crosstalk.
3. Suitable for reflow soldering.
4. Shapes and dimensions follow E.I.A. spec.
5. High Current Bead Low RDC
6. Excellent solder ability and heat resistance.
7. High reliability.
8. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
9. Low DC resistance structure of electrode to prevent wasteful electric power consumption.
10. Operating Temperature : -55~+125°C (Including self-temperature rise)

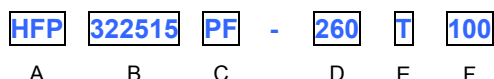


2. Dimensions



Chip size				
Size	A(mm)	B(mm)	C(mm)	D(mm)
322515	3.20±0.20	2.50±0.20	1.50+0.1/-0.2	0.70±0.30
322520	3.20±0.20	2.50±0.20	2.00±0.20	0.70±0.30

3. Part Numbering



- A: Series
 B: Dimension L x W x H
 C: Material Lead Free Material
 D: Impedance 260=26Ω
 E: Packaging T=Taping and Reel, B=Bulk(Bags)
 F: Rated Current 100=10000mA

4. Specification

Tai-Tech Part Number	Thickness C size (mm)	Impedance (Ω)	Test Frequency (Hz)	DC Resistance (Ω) max.	Rated Current (mA) max.
HFP322520PF-120T200	2.00±0.20	12±5	60mV/100M	0.0006	20000
HFP322515PF-260T100	1.50+0.1/-0.2	26±10	60mV/100M	0.0016	10000
HFP322520PF-300T100	2.00±0.20	30±10	60mV/100M	0.0016	10000

- Rated current: based on temperature rise test
- In compliance with EIA 595
- All test data referenced to 25°C ambient

Impedance Frequency Characteristics(Typical)

